Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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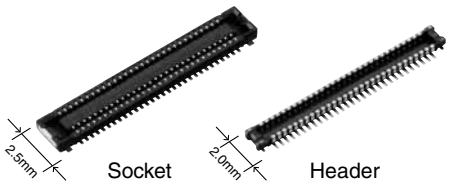
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

For board-to-FPC

High Current Connectors A35P

TOUGH CONTACT

New

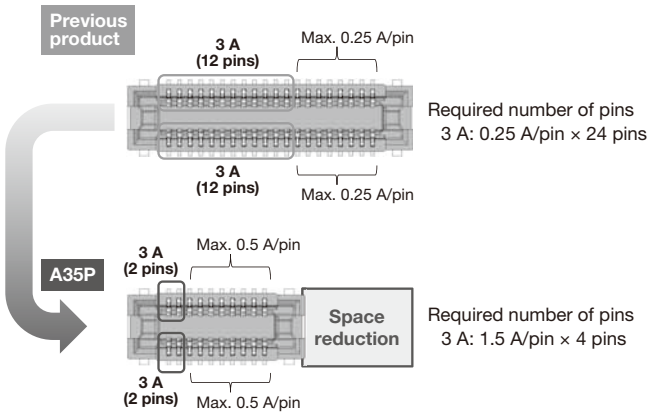


RoHS compliant

FEATURES

1. High current rating 5 A (using 1.25 A/pin × 8 pins)
2. Support of high current means number of pins can be reduced and design with space saving requirements.
• Reduced space with decrease in number of pins used for power contacts.

Example: Power line Max. 3 A (Pitch: 0.35 mm)



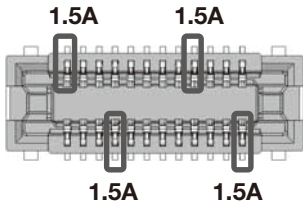
• Rated current

Number of power contacts	Rated current		
	Power contact	Signal contact	Total
Max. 4 pins	1.5 A/pin	0.5 A/pin	Max. 12 A
Max. 8 pins	1.25 A/pin		

Number of power contacts: 1.5 A/pin x 4 pins or 1.25 A/pin x 8 pins can be used

3. Increased design freedom (pin layout and multiple high current lines)
Any pin contact can be used as a power contact.
Any layout is possible for the power supply line.

Sample layout



*For 1.5 A/pin power contact
Other pin contacts can be up to max. 0.5 A (total of pin is max. 12 A).

4. Terminal pitch: 0.35 mm, width: 2.5 mm and Mated height: 0.8 mm

APPLICATIONS

• Connections between PC boards where there is a tendency for increased number of pins with the increase in charging current.
• Connection section of all modules where power consumption increases.

ORDERING INFORMATION

AXF □ □□ 1 2

5A: Socket
6A: Header

Number of pins (2 digits)

Mated height
<Socket> / <Header>
1: 0.8 mm

Functions
2: Without positioning bosses

PRODUCT TYPES

Mated height	Number of pins	Part number		Packing	
		Socket	Header	Inner carton (1-reel)	Outer carton
0.8mm	10	AXF5A1012	AXF6A1012	5,000 pieces	10,000 pieces
	12	AXF5A1212	AXF6A1212		
	16	AXF5A1612	AXF6A1612		
	20	AXF5A2012	AXF6A2012		
	24	AXF5A2412	AXF6A2412		
	30	AXF5A3012	AXF6A3012		
	34	AXF5A3412	AXF6A3412		
	40	AXF5A4012	AXF6A4012		
	44	AXF5A4412	AXF6A4412		
	50	AXF5A5012	AXF6A5012		
	54	AXF5A5412	AXF6A5412		
	60	AXF5A6012	AXF6A6012		
	64	AXF5A6412	AXF6A6412		
	70	AXF5A7012	AXF6A7012		
	80	AXF5A8012	AXF6A8012		
	100	AXF5A0012	AXF6A0012		

Notes: 1. Order unit:
For volume production: 1-inner carton (1-reel) units
For samples, please contact our sales office.
2. Please contact us for connectors having a number of pins other than those listed above.

SPECIFICATIONS

1. Characteristics

Item		Specifications	Conditions
Electrical characteristics	Rated current	1.5 A/pin contact × 4 pin contacts or 1.25 A/pin contact × 8 pin contacts (as power contact) 0.5 A/pin contact (as signal contact) (Max. 12 A at total pin contacts)	
	Rated voltage	30V AC/DC	
	Dielectric strength	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 30mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 0.981N/pin contact × pin contacts (initial)	
	Composite removal force	Min. 0.165N/pin contact × pin contacts	
	Contact holding force (Socket contact)	Min. 0.20N/pin contact	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	–55°C to +85°C	No icing or condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	–55°C to +85°C (product only) –40°C to +50°C (emboss packing)	No icing or condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 30mΩ	Conformed to MIL-STD-202F, method 107G Order / Temperature (°C) / Time (minutes) 1 / -55^{0}_{-3} / 30 2 / ⟆ / Max. 5 3 / 85^{+3}_{0} / 30 4 / ⟆ / Max. 5 -55^{0}_{-3}
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 30mΩ	Conformed to IEC60068-2-78 Bath temperature 40°C±2°C, humidity 90% to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 30mΩ	Conformed to IEC60068-2-11 Bath temperature 35°C±2°C, saltwater concentration 5%±1%
	H_2S resistance (header and socket mated)	48 hours, contact resistance max. 30mΩ	Bath temperature 40°C±2°C, gas concentration 3 ppm ±1 ppm, humidity 75% to 80% R.H.
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight		60 pin contact Socket 0.03 g Header 0.02 g	

2. Material and surface treatment

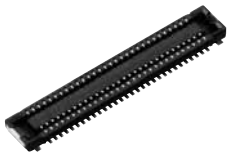
Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating, Surface: Au plating Terminal portion: Base: Ni plating, Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating, Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating, Surface: Au plating (except the terminal tips)

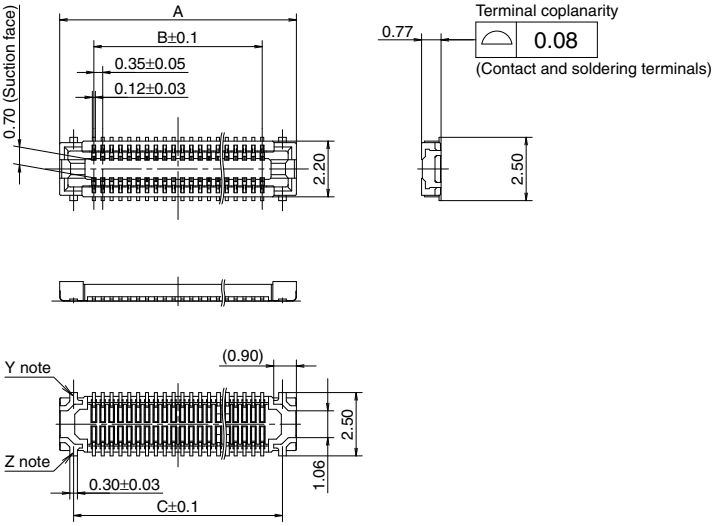
DIMENSIONS (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: http://industrial.panasonic.com/ac/e/

Socket (Mated height: 0.8 mm)

CAD Data





General tolerance: ±0.2

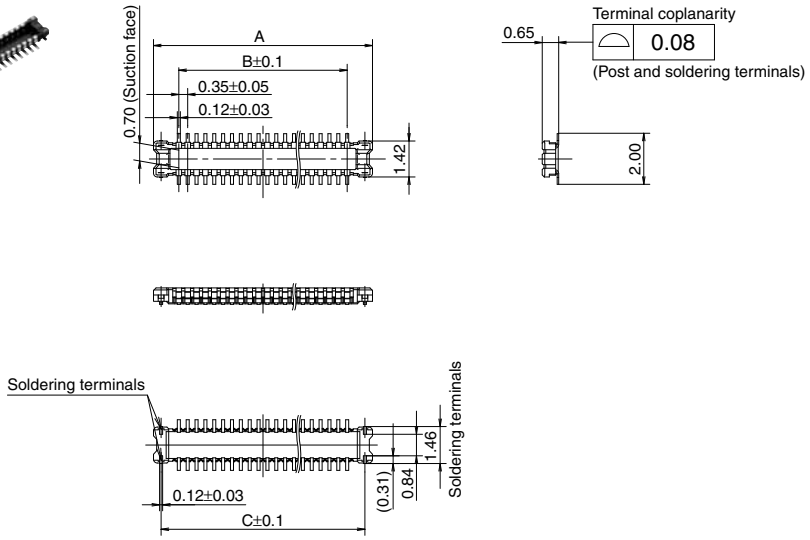
Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	4.10	1.40	3.00
12	4.45	1.75	3.35
16	5.15	2.45	4.05
20	5.85	3.15	4.75
24	6.55	3.85	5.45
30	7.60	4.90	6.50
34	8.30	5.60	7.20
40	9.35	6.65	8.25
44	10.05	7.35	8.95
50	11.10	8.40	10.00
54	11.80	9.10	10.70
60	12.85	10.15	11.75
64	13.55	10.85	12.45
70	14.60	11.90	13.50
80	16.35	13.65	15.25
100	19.85	17.15	18.75

Header (Mated height: 0.8 mm)

CAD Data

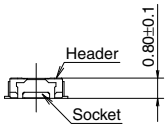


General tolerance: ±0.2

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	3.40	1.40	2.80
12	3.75	1.75	3.15
16	4.45	2.45	3.85
20	5.15	3.15	4.55
24	5.85	3.85	5.25
30	6.90	4.90	6.30
34	7.60	5.60	7.00
40	8.65	6.65	8.05
44	9.35	7.35	8.75
50	10.40	8.40	9.80
54	11.10	9.10	10.50
60	12.15	10.15	11.55
64	12.85	10.85	12.25
70	13.90	11.90	13.30
80	15.65	13.65	15.05
100	19.15	17.15	18.55

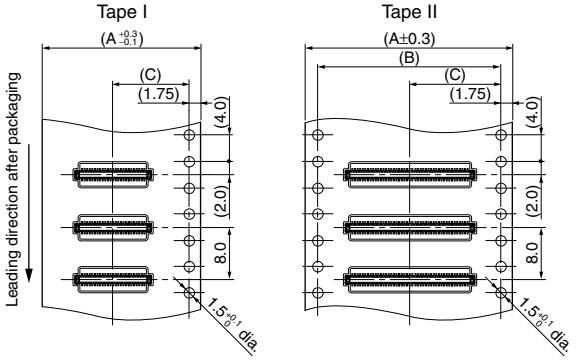
• Socket and Header are mated



EMBOSSED TAPE DIMENSIONS (Unit: mm)

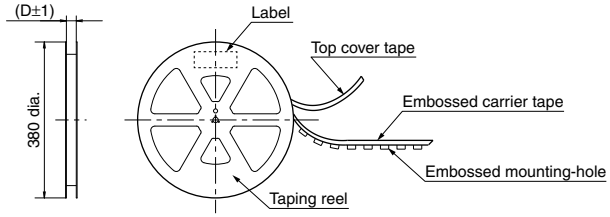
• Specifications for taping

(In accordance with JIS C 0806-3:1999. However, not applied to the mounting-hole pitch of some connectors.)



• Specifications for the plastic reel

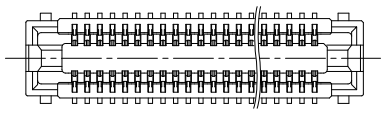
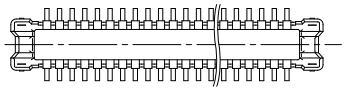
(In accordance with EIAJ ET-7200B.)



• Dimension table (Unit: mm)

Type/Mated height	Number of pins	Type of taping	A	B	C	D	Quantity per reel
Common for sockets and headers 0.8mm	10 to 24	Tape I	16.0	—	7.5	17.4	5,000
	30 to 80	Tape I	24.0	—	11.5	25.4	5,000
	100	Tape II	32.0	28.4	14.2	33.4	5,000

• Connector orientation with respect to embossed tape feeding direction

Direction of tape progress \ Type	Common for A35P
⬇	Socket  Header 

Note: There is no indication on this product regarding top-bottom or left-right orientation.

NOTES

■ Design of PC board patterns

Conduct the recommended foot pattern design, in order to preserve the mechanical strength of terminal solder areas.

■ Recommended PC board and metal mask patterns

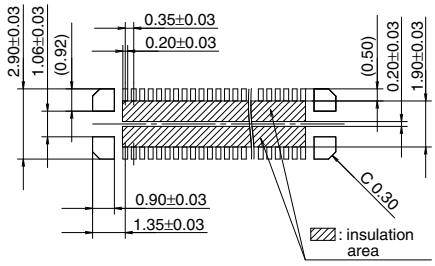
Connectors are mounted with high pitch density, intervals of 0.35 mm, 0.4 mm or 0.5 mm.

In order to reduce solder and flux rise, solder bridges and other issues make sure the proper levels of solder is used.

The figures to the right are recommended metal mask patterns. Please use them as a reference.

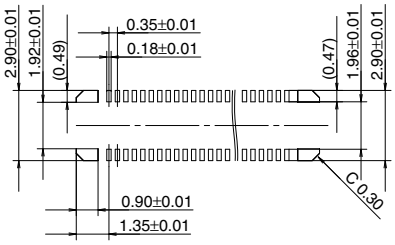
• Socket (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)



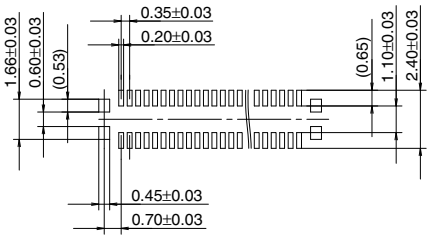
Recommended metal mask pattern

Metal mask thickness: When 100µm
(Terminal opening ratio: 85%)
(Metal-part opening ratio: 50%)



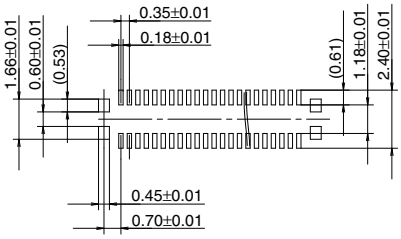
• Header (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)



Recommended metal mask pattern

Metal mask thickness: When 100µm
(Terminal opening ratio: 84%)
(Metal-part opening ratio: 100%)



Please refer to the latest product specifications when designing your product.

For board-to-board/board-to-FPC

Notes on Using Narrow pitch Connectors/ High Current Connectors

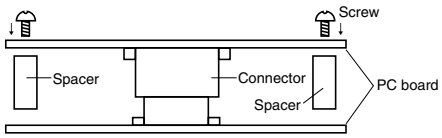
About safety Remarks

1) Do not use these connectors beyond the specification sheets. The usage outside of specified rated current, dielectric strength, and environmental conditions and so on may cause circuitry damage via abnormal heating, smoke, and fire.
2) In order to avoid accidents, your thorough specification review is appreciated.
Please contact us if your usage is out of the specifications. Otherwise, Panasonic Corporation cannot guarantee the quality and reliability.
3) Panasonic Corporation is consistently striving to improve quality and reliability. However, the fact remains that electrical components and devices generally cause failures at a given statistical probability. Furthermore, their durability varies with use environments or use conditions. In this respect, please check for actual electrical components and devices under actual conditions before use.
Continued usage in a state of degraded condition may cause the deteriorated insulation, thus result in abnormal heat, smoke or firing. Please carry out safety design and periodic maintenance including redundancy design, design for fire spread prevention, and design for malfunction prevention so that no accidents resulting in injury or death, fire accidents, or social damage will be caused as a result of failure of the products or ending life of the products.

Regarding the design of devices and PC board patterns

1) When using the board to board connectors, do not connect a pair of board with multiple connectors.
Otherwise, misaligned connector positions may cause mating failure or product breakage.
2) With mounting equipment, there may be up to a ±0.2 to 0.3-mm error in positioning. Be sure to design PC boards and patterns while taking into consideration the performance and abilities of the required equipment.
3) Some connectors have tabs embossed on the body to aid in positioning. When using these connectors, make sure that the PC board is designed with positioning holes to match these tabs.
4) To ensure the required mechanical strength when soldering the connector terminals, make sure the PC board meets recommended PC board pattern design dimensions given.
5) PC board
Control the thicknesses of the coverlay and adhesive to prevent poor soldering. This connector has no stand-off.
Therefore, minimize the thickness of the coverlay, etc. so as to prevent the occurrence of poor soldering.
6) For all connectors of the narrow pitch series, to prevent the PC board from coming off during vibrations or impacts, and to prevent loads from falling directly on the soldered portions, be sure to design some means to fix the PC board in place.

Example) Secure in place with screws



When connecting PC boards, take appropriate measures to prevent the connector from coming off.
7) When mounting connectors on a FPC board:
• When the connector soldered to FPC is mated or unmated, solder detachment may occur by the force to the terminals. Connector handling is recommended in the condition when the reinforcing plate is attached to the backside of FPC where the connector is mounted. The external dimension of the reinforcing plate is recommended to be larger than the dimension of “PC board recommended process pattern” (extended dimension of one side is approximately 0.5 to 1.0 mm). The materials and thickness of the reinforcing plate are glass epoxy or polyimide (thickness 0.2 - 0.3 mm) or SUS (thickness 0.1 - 0.2 mm).
• As this connector has temporary locking structure, the connector mating may be separated by the dropping impact depend on the size, weight or bending force of the FPC. Please consider the measures at usage to prevent the mating separation.
8) The narrow pitch connector series is designed to be compact and thin. Although ease of handling has been taken into account, take care when mating the connectors, as displacement or angled mating could damage or deform the connector.

Regarding the selection of the connector placement machine and the mounting procedures

1) Select the placement machine taking into consideration the connector height, required positioning accuracy, and packaging conditions.
2) Be aware that if the chucking force of the placement machine is too great, it may deform the shape of the connector body or connector terminals.
3) Be aware that during mounting, external forces may be applied to the connector contact surfaces and terminals and cause deformations.
4) Depending on the size of the connector being used, self alignment may not be possible. In such cases, be sure to carefully position the terminal with the PC board pattern.
5) The positioning bosses give an approximate alignment for positioning on the PC board. For accurate positioning of the connector when mounting it to the PC board, we recommend using an automatic positioning machine.
6) In case of dry condition, please note the occurrence of static electricity.
The product may be adhered to the embossed carrier tape or the cover tape in dry condition.
Recommended humidity is from 40%RH to 60%RH and please remove static electricity by ionizer in manufacturing process.

Regarding soldering

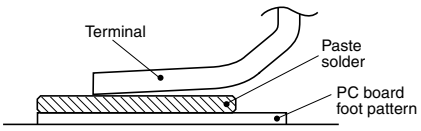
■ Reflow soldering

1) Measure the recommended profile temperature for reflow soldering by placing a sensor on the PC board near the connector surface or terminals. (Please refer to the specification for detail because the temperature setting differs by products.)

2) As for cream solder printing, screen printing is recommended.

3) When setting the screen opening area and PC board foot pattern area, refer the recommended PC board pattern and window size of metal mask on the specification sheet, and make sure that the size of board pattern and metal mask at the base of the terminals are not increased.

4) Please pay attentions not to provide too much solder. It makes miss mating because of interference at soldering portion when mating.



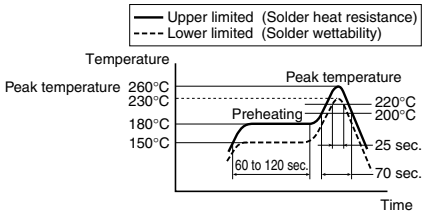
5) When mounting on both sides of the PC board and the connector is mounting on the underside, use adhesives or other means to ensure the connector is properly fixed to the PC board. (Double reflow soldering on the same side is possible.)

6) The condition of solder or flux rise and wettability varies depending on the type of solder and flux. Solder and flux characteristics should be taken into consideration and also set the reflow temperature and oxygen level.

7) Do not use resin-containing solder. Otherwise, the contacts might be firmly fixed.

8) Soldering conditions

Please use the reflow temperature profile conditions recommended below for reflow soldering. Please contact us before using a temperature profile other than that described below (e.g. lead-free solder).



For products other than the ones above, please refer to the latest product specifications.

9) The temperature profiles given in this catalog are values measured when using the connector on a resin-based PC board. When performed reflow soldering on a metal board (iron, aluminum, etc.) or a metal table to mount on a FPC, make sure there is no deformation or discoloration of the connector before mounting.

10) Consult us when using a screen-printing thickness other than that recommended.

■ Hand soldering

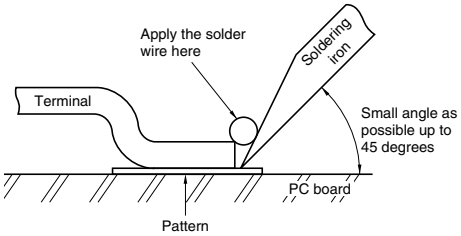
1) Set the soldering iron so that the tip temperature is less than that given in the table below.

Table A

Product name	Soldering iron temperature
SMD type connectors	300°C within 5 sec. 350°C within 3 sec.

2) Do not allow flux to spread onto the connector leads or PC board. This may lead to flux rising up to the connector inside.

3) Touch the soldering iron to the foot pattern. After the foot pattern and connector terminal are heated, apply the solder wire so it melts at the end of the connector terminals.



4) Be aware that soldering while applying a load on the connector terminals may cause improper operation of the connector.

5) Thoroughly clean the soldering iron.

6) Flux from the solder wire may get on the contact surfaces during soldering operations. After soldering, carefully check the contact surfaces and clean off any solder before use.

7) These connector is low profile type. If too much solder is supplied for hand soldering, It makes miss mating because of interference at soldering portion. Please pay attentions.

■ Solder reworking

1) Finish reworking in one operation.

2) In case of soldering rework of bridges. Don't use supplementary solder flux. Doing so may cause contact problems by flux.

3) Keep the soldering iron tip temperature below the temperature given in Table A.

Handling Single Components

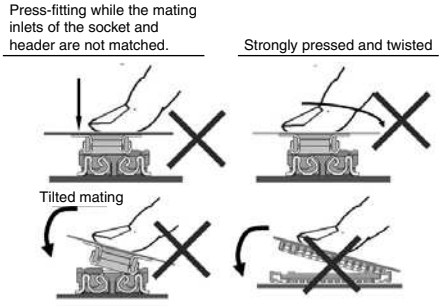
1) Make sure not to drop or allow parts to fall from work bench.

2) Excessive force applied to the terminals could cause warping, come out, or weaken the adhesive strength of the solder. Handle with care.

3) Do not insert or remove the connector when it is not soldered. Forcibly applied external pressure on the terminals can weaken the adherence of the terminals to the molded part or cause the terminals to lose their evenness.

Precautions for mating

This product is designed with ease of handling. However, in order to prevent the deformation or damage of contacts and molding, take care and do not mate the connectors as shown right.

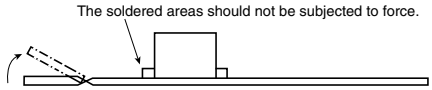


Cleaning flux from PC board

There is no need to clean this product. If cleaning it, pay attention to the following points to prevent the negative effect to the product.
1) Keep the cleaning solvent clean and prevent the connector contacts from contamination.
2) Some cleaning solvents are strong and they may dissolve the molded part and characters, so pure water passed liquid solvent is recommended.

Handling the PC board after mounting the connector

When cutting or bending the PC board after mounting the connector, be careful that the soldered sections are subjected to excessive force.



Storage of connectors

1) To prevent problems from voids or air pockets due to heat of reflow soldering, avoid storing the connectors in areas of high humidity.
2) Depending on the connector type, the color of the connector may vary from connector to connector depending on when it is produced. Some connectors may change color slightly if subjected to ultraviolet rays during storage. This is normal and will not affect the operation of the connector.
3) When storing the connectors with the PC boards assembled and components alreeady set, be careful not to stack them up so the connectors are subjected to excessive forces.
4) Avoid storing the connectors in locations with excessive dust. The dust may accumulate and cause improper connections at the contact surfaces.

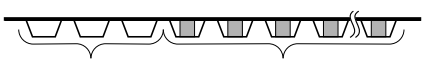
Other Notes

1) Do not remove or insert the electrified connector (in the state of carrying current or applying voltage).
2) Dropping of the products or rough mishandling may bend or damage the terminals and possibly hinder proper reflow soldering.
3) Before soldering, try not to insert or remove the connector more than absolutely necessary.
4) When coating the PC board after soldering the connector to prevent the deterioration of insulation, perform the coating in such a way so that the coating does not get on the connector.
5) There may be variations in the colors of products from different production lots. This is normal.
6) The connectors are not meant to be used for switching.
7) Product failures due to condensation are not covered by warranty.

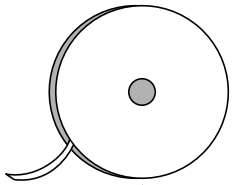
Regarding sample orders to confirm proper mounting

When ordering samples to confirm proper mounting with the placement machine, connectors are delivered in 50-piece units in the condition given right. Consult a sale representative for ordering sample units.

Condition when delivered from manufacturing



Embossed tape amount required for the mounting	Required number of products for sample production (Unit 50 pcs.)



Reel
(Delivery can also be made on a reel by customer request.)

Please refer to the latest product specifications when designing your product.

Please contact .....

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